





(2.00 mm) .0787"

EBTM SERIES

ExaMAX® BACKPLANE HEADER

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?EBTM

Insulator Material:
Liquid Crystal Polymer
Contact Material:
Copper Alloy
Plating:
Sn or Au over
50 μ" (1.27 μm) Ni
Operating Temp Range:
-55 °C to +85 °C
Current Rating:
4.2 A per pin
(1 pin powered per row)
Contact Wipe:
2.4 mm
RoHS Compliant:

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality

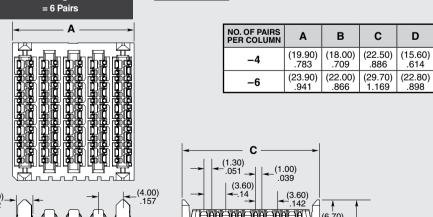


ALSO AVAILABLE (MOQ Required)

- Staging
- Guidance
- Keying
- End walls

Contact Samtec.

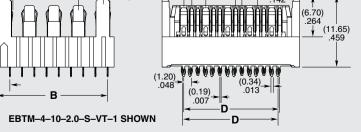
Provides 2.00 mm exceptionally Mates with: column pitch low mating force while maintaining excellent normal force **APPLICATION** Two reliable points of contact Press-fit with 2.4 mm wipe termination NO. OF PAIRS **COLUMN EBTM** COLUMNS **PLATING** PER COLUMN **PITCH** -2.0 -10 = (2.0 mm) (–4 only) -4 .0787" = 30 μ" (0.76 μm) Gold in contact area, Matte Tin on tail = 4 Pairs **-12** (-6 only) -6 = 6 Pairs



Notes:

Some lengths, styles and options are non-standard, non-returnable.

ExaMAX® is a trademark of AFCI.



Due to technical progress, all designs, specifications and components are subject to change without notice